PIN 1 INDEX

5

2.5

A

DETAIL G

M

0.15 C
2X

5

2.5

B

0.15 C
2X

2.2
1.8

1

0.1 Ⓜ C A B

EXPOSED
DIE
ATTACH PAD

14 16

13 1

DETAIL M

2.2
1.8

0.1 Ⓜ C A B

1

8X 0.8

9 5

8 6

12X 0.62
0.48

0.1 Ⓜ C A B
0.05 Ⓜ C

20X 1.175
0.925

VIEW M–M

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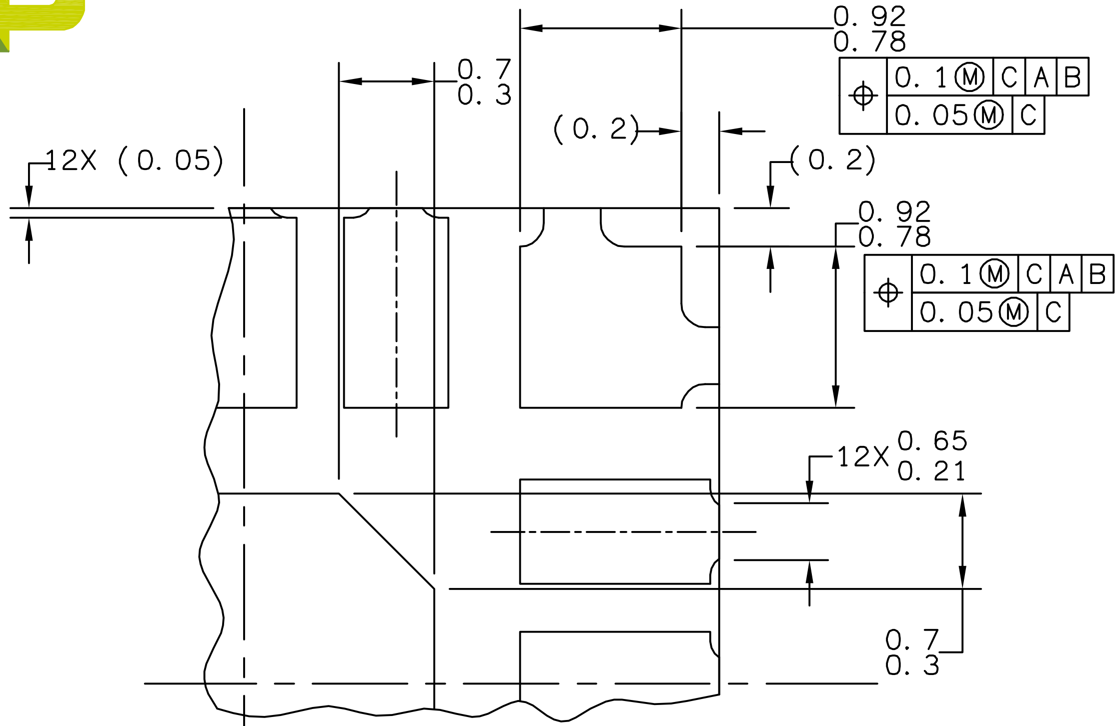
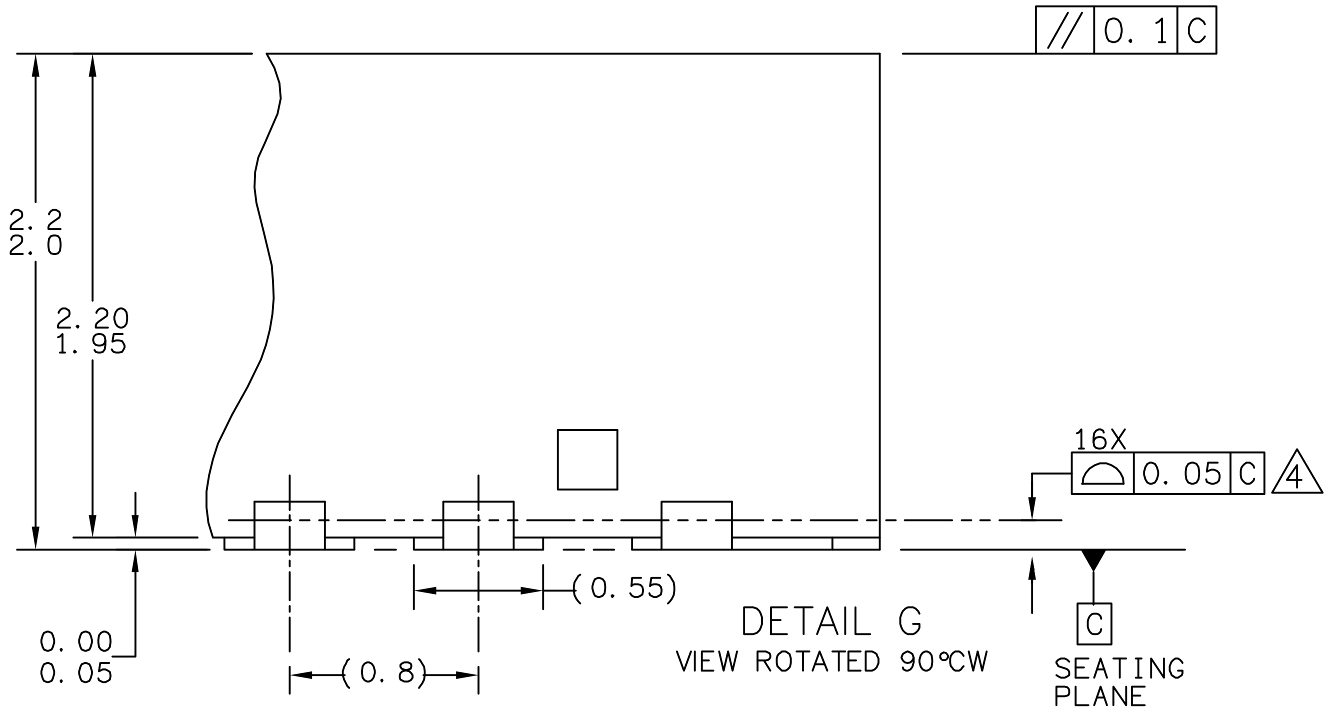
TITLE: THERMALLY ENHANCED POWER QUAD FLAT NON–LEADED PACKAGE (PQFN) 16 TERMINAL, 0.8 PITCH (5X5X2.1) CASE OUTLINE	DOCUMENT NO: 98ARL10575D	REV: G
	STANDARD: JEDEC MO–251	
	SOT1632–1	30 DEC 2015



DETAIL M

CORNER CONFIGURATION



DETAIL G

VIEW ROTATED 90°CW

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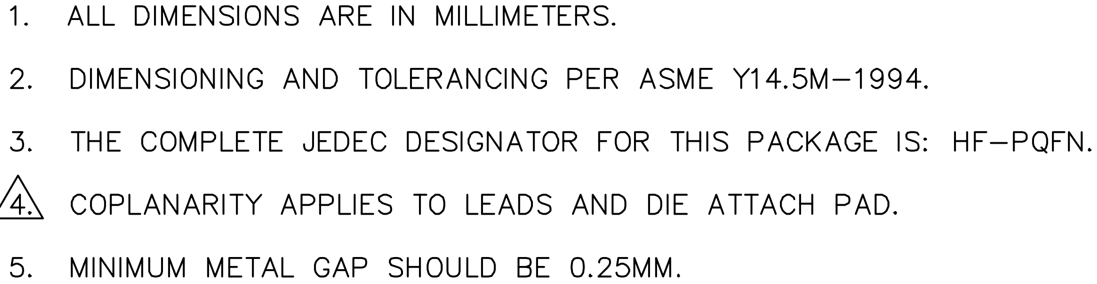
NOTES:



1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
4. (4△) COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MINIMUM METAL GAP SHOULD BE 0.25MM.

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